

September 16, 2015

Datasheet Errata for the S6E2D3 Series 32-bit ARM® Cortex®-M4F, FM4 Microcontroller

This document describes the errata for the S6E2D3 Series 32-bit ARM® Cortex®-M4F, FM4 Microcontroller. Compare this document to the device's data sheet for a complete functional description.

Contact your local Cypress Sales Representative if you have questions.

Part Numbers Affected

Part Number
S6E2D3 Series

Page	Item	Description
Original document code: DS709-00023-1v0-E		
Rev. 1.0 June 25, 2015		
64	9. Handling Devices	"Sub Crystal Oscillator" should be added as indicated by shading below. ■ Surface mount type - Size: More than 3.2 mm × 1.5 mm - Load capacitance: Approximately 6 pF to 7 pF When the Standard setting (CCS/CCB=11001110) - Load capacitance: Approximately 4 pF to 7 pF When the low power setting (CCS/CCB=00000100) ■ Lead type - Load capacitance: Approximately 6 pF to 7 pF When the Standard setting (CCS/CCB=11001110) - Load capacitance: Approximately 4 pF to 7 pF When the low power setting (CCS/CCB=00000100)

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92	14.3.1 Current Rating	Table 14-10 should be added as indicated by the shading below. Table 14-10 Typical and Maximum Current Consumption in Deep Standby Stop Mode, Deep Standby RTC Mode and VBAT <table><tr><th rowspan="2">Parameter</th><th rowspan="2">Symbol</th><th rowspan="2">Pin Name</th><th rowspan="2">Conditions</th><th rowspan="2">Frequency (MHz)</th><th colspan="2">Value</th><th rowspan="2">Unit</th><th rowspan="2">Remarks</th></tr><tr><th>Typ</th><th>Max</th></tr><tr><td rowspan="9">Power supply current</td><td rowspan="9">ICCVBAT</td><td rowspan="9">VBAT</td><td rowspan="3">RTC stop</td><td rowspan="9">-</td><td>0.009</td><td>0.032</td><td>μA</td><td>*3, *4, *5 T_A=+25°C</td></tr><tr><td>-</td><td>0.994</td><td>μA</td><td>*3, *4, *5 T_A=+85°C</td></tr><tr><td>-</td><td>1.491</td><td>μA</td><td>*3, *4, *5 T_A=+105°C</td></tr><tr><td colspan="2">RTC *6 operation</td><td>1.0</td><td>1.636</td><td>μA</td><td>*3, *4 T_A=+25°C</td></tr><tr><td colspan="2">RTC *6 operation</td><td>-</td><td>2.828</td><td>μA</td><td>*3, *4 T_A=+85°C</td></tr><tr><td colspan="2">RTC *6 operation</td><td>-</td><td>4.242</td><td>μA</td><td>*3, *4 T_A=+105°C</td></tr><tr><td colspan="2">RTC *7 operation</td><td>0.7</td><td>1.153</td><td>μA</td><td>*3, *4 T_A=+25°C</td></tr><tr><td colspan="2">RTC *7 operation</td><td>-</td><td>2.277</td><td>μA</td><td>*3, *4 T_A=+85°C</td></tr><tr><td colspan="2">RTC *7 operation</td><td>-</td><td>3.416</td><td>μA</td><td>*3, *4 T_A=+105°C</td></tr></table> *1: V_{CC}=3.3 V *2: V_{CC}=3.6 V *3: When all ports are fixed. *4: When LVD is OFF *5: When sub oscillation is OFF *6: When using the crystal oscillator of 32 kHz (including the current consumption of the oscillation circuit) When the Standard setting (CCS/CCB=11001110) *7: When using the crystal oscillator of 32 kHz (including the current consumption of the oscillation circuit) When the low power setting (CCS/CCB=00000100)	Parameter	Symbol	Pin Name	Conditions	Frequency (MHz)	Value		Unit	Remarks	Typ	Max	Power supply current	ICCVBAT	VBAT	RTC stop	-	0.009	0.032	μA	*3, *4, *5 T _A =+25°C	-	0.994	μA	*3, *4, *5 T _A =+85°C	-	1.491	μA	*3, *4, *5 T _A =+105°C	RTC *6 operation		1.0	1.636	μA	*3, *4 T _A =+25°C	RTC *6 operation		-	2.828	μA	*3, *4 T _A =+85°C	RTC *6 operation		-	4.242	μA	*3, *4 T _A =+105°C	RTC *7 operation		0.7	1.153	μA	*3, *4 T _A =+25°C	RTC *7 operation		-	2.277	μA	*3, *4 T _A =+85°C	RTC *7 operation		-	3.416	μA	*3, *4 T _A =+105°C
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10	2. Features	Note should be added as indicated by the shading below. (Error) GDC Unit ■ Controller for external graphics display ■ Accelerator for 2D block image transfer (blit) operations ■ Embedded SRAM video memory ■ High-Speed Quad SPI (Serial Peripheral Interface for external memory extensions) ■ SDRAM interface for external memory extensions ■ HBI (Hyper Bus Interface) interface for external memory extensions ■ Maximum core system clock frequency : 160 MHz (Correct) GDC Unit ■ Controller for external graphics display ■ Accelerator for 2D block image transfer (blit) operations ■ Embedded SRAM video memory ■ High-Speed Quad SPI (Serial Peripheral Interface for external memory extensions) ■ SDRAM interface for external memory extensions ■ HBI (Hyper Bus Interface) interface for external memory extensions ■ Maximum core system clock frequency : 160 MHz Note: - User can leverage the internal VRAM and external HyperRAM as a graphics memory allowed to be written by GDC.																																								
15	4. Packages	“Packages” should be corrected as indicated by the shading below. (Error) <table><tr><th>Package \ Product Name</th><th>S6E2D35G0A</th><th>S6E2D35J0A</th><th>S6E2D35GJA</th></tr><tr><td>LQFP: FPT-120P-M21 (0.5 mm pitch)</td><td>○</td><td>-</td><td>○</td></tr><tr><td>LQFP: FPT-176P-M07 (0.5 mm pitch)</td><td>-</td><td>○</td><td>-</td></tr><tr><td>PFBGA: FDJ161 (0.5 mm pitch)</td><td>○</td><td>-</td><td>-</td></tr><tr><td>Ex_LQFP(TEQFP): LEM120 (0.5 mm pitch)</td><td>○</td><td></td><td></td></tr></table> ○: Supported (Correct) <table><tr><th>Package \ Product Name</th><th>S6E2D35G0A</th><th>S6E2D35J0A</th><th>S6E2D35GJA</th></tr><tr><td>LQFP: FPT-120P-M21 (0.5 mm pitch)</td><td>○</td><td>-</td><td>○</td></tr><tr><td>LQFP: FPT-176P-M07 (0.5 mm pitch)</td><td>-</td><td>○</td><td>-</td></tr><tr><td>FPGA: FDJ161 (0.5 mm pitch)</td><td>○</td><td>-</td><td>-</td></tr><tr><td>Ex_LQFP(TEQFP): LEM120 (0.5 mm pitch)</td><td>■</td><td>■</td><td>■</td></tr></table> ○: Supported ■: In development	Package \ Product Name	S6E2D35G0A	S6E2D35J0A	S6E2D35GJA	LQFP: FPT-120P-M21 (0.5 mm pitch)	○	-	○	LQFP: FPT-176P-M07 (0.5 mm pitch)	-	○	-	PFBGA: FDJ161 (0.5 mm pitch)	○	-	-	Ex_LQFP(TEQFP): LEM120 (0.5 mm pitch)	○			Package \ Product Name	S6E2D35G0A	S6E2D35J0A	S6E2D35GJA	LQFP: FPT-120P-M21 (0.5 mm pitch)	○	-	○	LQFP: FPT-176P-M07 (0.5 mm pitch)	-	○	-	FPGA: FDJ161 (0.5 mm pitch)	○	-	-	Ex_LQFP(TEQFP): LEM120 (0.5 mm pitch)	■	■	■
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Document History Page

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Rev.	ECN No.	Orig. of Change	Description of Change
**	—	AKIH	Initial release.
*A	5158612	AKIH	Migrated Spansion Errata sheet from S6E2D3_DS709-00023-1v0-E-DE2 to Cypress format

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